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TITLE: PBGA, LOW PROFILE, FINE PITCH, 489 I/O, 19 X 19 PKG, 0.8 MM PITCH (MAP)	DOCUMENT NO: 98ASA00192D	REV: 0	
	CASE NUMBER: 2115-01	01 FEB 2010	
	STANDARD: JEDEC-MO-275-PPAC-1		



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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